



NEW PRODUCT SPEC SHEET

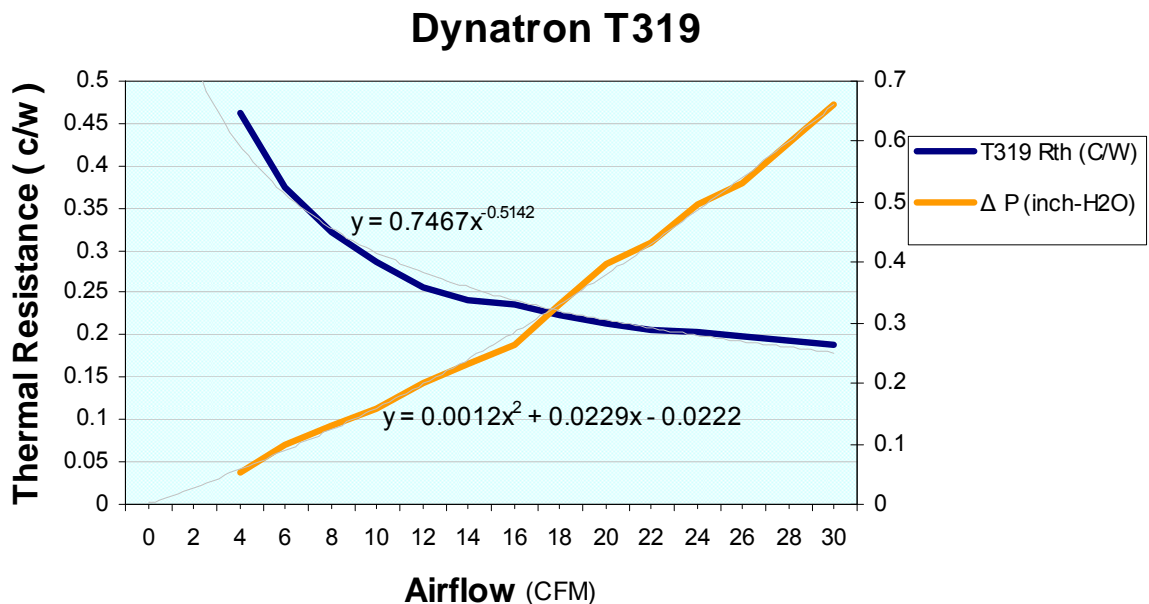
Model Number: T319

- Recommend for AMD Opteron™ 4100 and 4200 Series Processor, Socket C32
Six-Core and Quad-Core AMD Opteron™ Processor, Socket F (1207)
- Passive Cooler for 1U Server

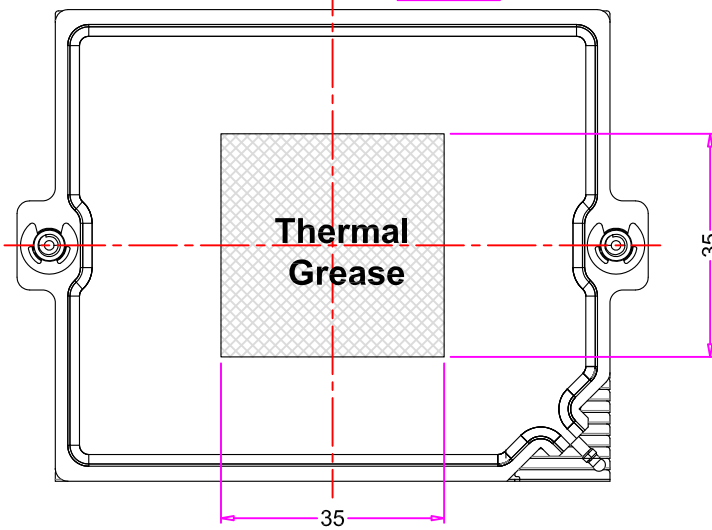
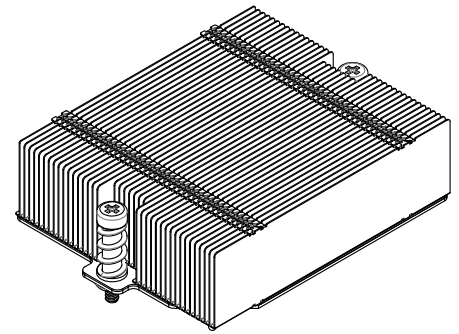
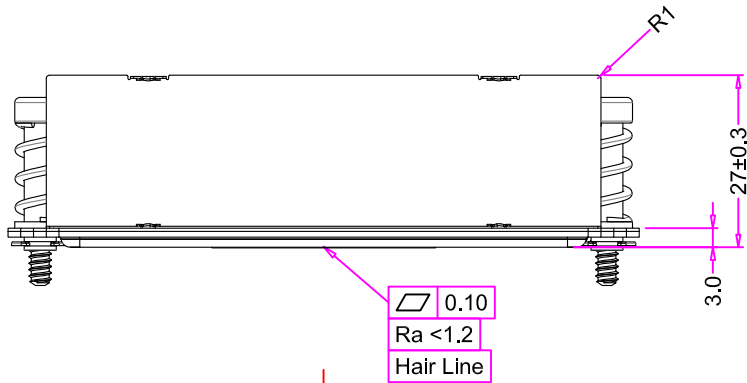
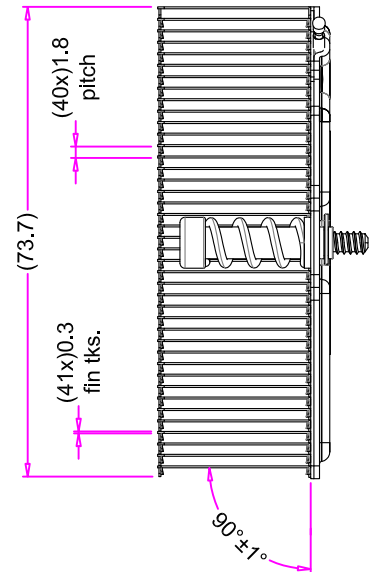
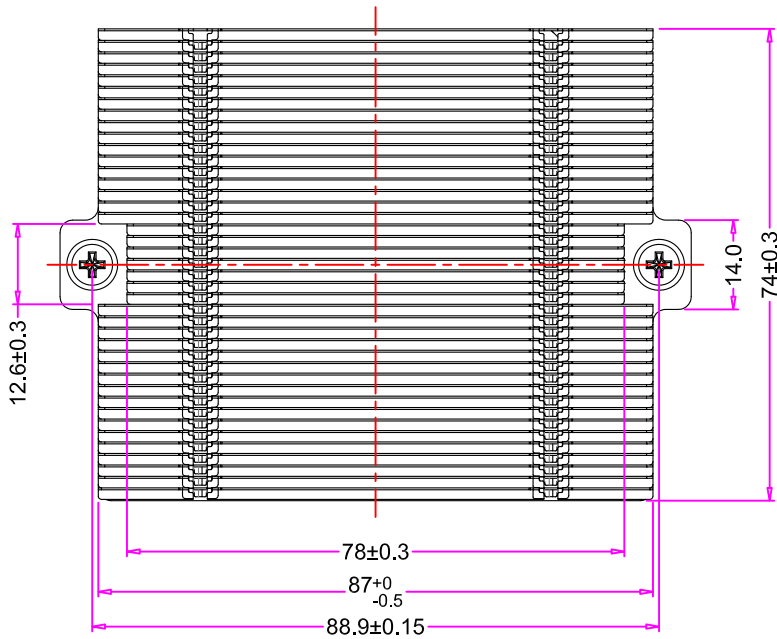
Overall Specification:

- Dimension: 87.0 x 74.0 x 27.0mm
- Weight: 430g± 5g
- Copper Stacked Fin Soldered on Copper Vapor Chamber Base
- Shin-Etsu G751 Thermal Grease Pre-Printed
- Support CPU Power up to 105 Watts Dissipation
- Backplate is not included

Passive Cooler T319 Thermal Performance in Wind Tunnel Simulation:



ITEM#	DESCRIPTION	CHECKER	DATE
1	Initial Release	LANG	06/22/12



NOTES,

1. UNIT: MM
2. BOTTOM SURFACE BY GRINDING PROCESS
3. SOLDERING BONDING BETWEEN FIN & BASE
4. REMOVE ALL BURRS & SHAPR EDGES
5. FINAL PASSIVATED TREATMENT
6. BACKPLATE IS NOT INCLUDED

ITEM#	DESCRIPTION	MATERIAL	QTY.
6	THERMAL GREASE, PREPRINTED	SHIN-ETSU G751	1
5	C-RING	STEEL	4
4	WASHER	STEEL	4
3	HEATSINK, STACKED FIN	VAPOR CHAMBER BASE COPPER 1100 FIN	1
2	SPRING	SUS304 (890G)	4
1	SCREW, HEATSINK, #6-32UNC	STEEL	4

	NAME	DATE
DRAWN BY	Engr.	06/22/2012
CHECKED BY	LANG	06/22/2012
ENG.APPROVED		
MFG.APPROVED	-	-



DYNATRON CORPORATION

TITLE: **1U Passive Vapor Chamber Heatsink T319
BOM & Overall Dimension Drawing**

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VIEW		DWG. No:	DYN-BD-T319	REV.	00
UNITS	MM				